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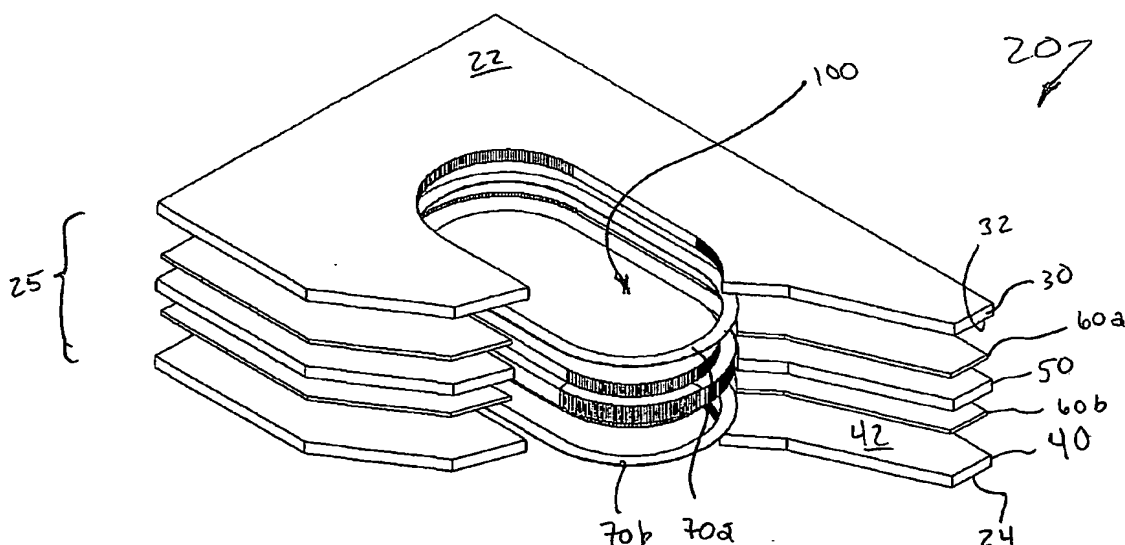
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(54) Title: MICROELECTRONIC SUBSTRATES WITH THERMALLY CONDUCTIVE PATHWAYS AND METHODS OF MAKING SAME



(57) Abstract: This disclosure suggests microelectronic substrates with thermally conductive pathways. In one implementation, such a substrate includes a body and a thermally conductive member. The Body has a first surface that includes a microelectronic component mounting site, a second surface separated from the first surface by a thickness, and an opening extending through at least a portion of the thickness. The opening is outwardly open at one or both of the surfaces and has a first portion having a first transverse dimension and a second portion having a larger second transverse dimension. The thermally conductive member includes a first thickness, which is received in the first portion of the opening, and a second thickness, which is received in the second portion of the opening. A transverse dimension of the second thickness of the thermally conductive member is greater than the first transverse dimension of the opening.

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